ABSTRACT OF THE DISCLOSURE

A pluggable optical packaging structure is provided, including: a substrate, a carrier ring, at least one optical connection assembly and a cover plate; the substrate includes at least one electronic integrated circuit (EIC) and at least one photonic integrated circuit (PIC); the carrier ring is located on the substrate, and the EIC and PIC are enclosed by the carrier ring; the optical connection assembly includes at least one socket, at least one connector, a plurality of optical fibers and at least one optical fiber array connector, the socket is located in a partial section of the carrier ring, the connector is in the socket, the optical fibers has one end coupled to the connector, the other end coupled to the fiber array connector, and is coupled to the PIC through the fiber array connector; the cover plate is located on the carrier ring and extends inwardly to above the PIC.

FIG. 1